

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SEUNG-HYUN LEE	03/17/2014
HYUN-KI LEE	03/17/2014
MIN-YOUNG KIM	03/17/2014
JEA-HONG LEE	03/17/2014
RECEIVING PARTY DATA	
Name:	KOH YOUNG TECHNOLOGY INC.
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Postal Code:	153-706
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Street Address:	1370, SANGYEOK 3(SAM)-DONG, BUK-GU
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Postal Code:	702-701
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14347137
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ATTORNEY DOCKET NUMBER:	CMP-0075-KY

NAME OF SUBMITTER:	JAE Y. PARK
SIGNATURE:	/Jae Y. Park/
DATE SIGNED:	03/25/2014
Total Attachments: 2 source=Assmt_CMP0075#page1.tif source=Assmt_CMP0075#page2.tif	

UNITED STATES PATENT RIGHTS, OR
UNITED STATES PLUS ALL FOREIGN PATENT RIGHTS

ASSIGNMENT

Insert Name(s)
and Address(es)
of Inventor(s) WHEREAS, Seung-Hyun LEE of 460-1, Eumnam-dong, Buk-gu, Daegu, 702-847
Republic of Korea; Hyun-KI LEE of #103-707, Sanjang Minuon, Manchon 3(sam)-dong,
Samseong-gu, Daegu, 706-760 Republic of Korea; Min-Young KIM of #102-505, Samsung
Cherwill Apt., Beomeo 4(sa)-dong, Suseong-gu, Daegu 706-014 Republic of Korea; Jea-Hong
LEE of 1905-5, Namde-dong, Jung-gu, Ulsan, 681-800 Republic of Korea
(hereinafter designated as the undersigned) has (have) invented certain new and useful improvements in

Insert Title
of Invention METHOD OF GENERATING HEIGHT INFORMATION IN CIRCUIT BOARD INSPECTION
APPARATUS
which claims priority to Korean Application No(s) 10-2011-0143531, filed on December 27, 2011, and
for which the undersigned is (are) about to file an application for Letters Patent of the United States; and

Insert Name(s)
and Address(es)
of Assignee(s) WHEREAS, KOH YOUNG TECHNOLOGY INC. of 13F Halla Sigma Valley, 345-90
Gasan-dong, Geumcheon-gu, Seoul, 153-706 Republic of Korea; and KYUNGPOOK
NATIONAL UNIVERSITY INDUSTRY ACADEMIC COOPERATION
FOUNDATION of 1370, Sangyeok 3(sam)-dong, Buk-gu, Daegu, 702-701 Republic of
Korea

its heirs, successors, legal representatives and assigns (hereinafter designated as the Assignee) are desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent(s) that may be granted therefor in the United States of America and in any foreign countries.

NOW, THEREFORE, to all whom it may concern, be it known that, for good and valuable consideration paid to the undersigned, the receipt of which is hereby acknowledged, the undersigned has (have) sold, assigned and transferred, and by these presents does sell, assign and transfer unto the Assignee the full and exclusive right to the said invention in the United States of America, its territories, dependencies and possessions; and the entire right, title and interest in and to any and all Letters Patent(s) which may be granted therefor in the United States of America, its territories, dependencies and possessions, and in any and all foreign countries;

and to any and all divisions, reissues, continuations, conversions and extensions thereof for the full term or terms for which the same may be granted.

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional, conversion or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

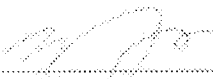
The undersigned agree (s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation, division, conversion or reissue thereof or Letter Patent(s) or reissue patent issued thereon and to cooperate with the Assignee in every way possible in obtaining and producing evidence and proceeding with such interference.

The undersigned agree(s) to execute all papers and documents and to perform any act which may be necessary in connection with claims or provisions of the International Convention for the Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States of America patent(s) or a grant of a valid United States of America and any foreign patent(s) to the Assignee and to vest all rights therein hereby conveyed to said Assignee as fully and entirely as the same would have been held by the undersigned if this Assignment and sale had not been made.

The undersigned hereby authorize(s) and request(s) the Patent and Trademark Office Officials in the United States of America and in any foreign countries to issue any and all Letters Patents resulting from said application or any continuing, divisional conversion or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) the full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

The undersigned declare that all statements made herof of his own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine (or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Name of inventor: Seung-Hyun LEE, Signature  Date Mar 19th 2014

Name of inventor: Hyun-Ki LEE, Signature 01 20 14 Date Mar 19th 2014

Name of inventor: Min-Young KIM, Signature  Date Mar 17th 2014

Name of inventor: Jea-Hong LEE, Signature Jea-Hong Lee Date Mar 19th 2014